

Fabrication Parameters:

Number of layers:	<b>2</b>
Board name:	<b>lazer.brd</b>
Board width (dimension X):	<b>140.000000 mm</b>
Board length (dimension Y):	<b>30.000000 mm</b>
Board thickness:	<b>1.570000 mm</b>
Copper thickness outer layers:	<b>0.035000 mm</b>
Copper thickness inner layers:	<b>undefined</b>
Solder sides:	<b>Both Sides</b>
Silkscreen sides:	<b>Top Side</b>
Number of SMD pads on top:	<b>0</b>
Number of SMD pads on bottom:	<b>0</b>
Number of blind or buried hole types:	<b>0</b>
Minimum trace width (track width):	<b>0.508000 mm</b>
Minimum SMD pitch:	<b>0.152400 mm</b>
Minimum hole size:	<b>1.016000 mm</b>

Assembly Parameters:

Number of different packages:	<b>2</b>
Number of BGAs:	<b>0</b>
Number of QFNs:	<b>0</b>
Number of fine pitch packages:	<b>0</b>
Number of other SMDs:	<b>0</b>
Number of thru hole packages:	<b>5</b>
SMDs on both sides:	<b>No</b>